

RF 15 N - Tactile switch, non-illuminated, silver contacts

3.14.100.606/0000

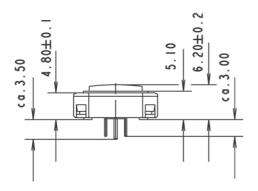
For keycaps, refer to RK 90 system design.

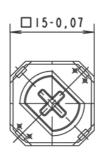


Page 2007 Pag	General information	
Length	Recommended key grid	19.05 mm
Length		
Width 15 mm Overall height 6.2 mm Mechanical design soldering in PCB Terminals THT Contact system snap-action contact Contact system 1 NO Contact materials Ag Illumination external 3 mm LED possible if height more than 12 mm Mechanical characteristics external 3 mm LED possible if height more than 12 mm Mechanical characteristics N Switching travel 0.5*0.2 mm Robustness max. 100 with through-plated PCB N Electrical characteristics Interpretation of the plate of the		
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Wave soldering 260 °C max.	Operating life min. (operations)	1,000,000 cycle
	Solderability / solder heat resistance	according to DIN EN 60068-2-20
Manual soldering 350 °C / 5 sec. max.	Wave soldering	260 °C max.
	Manual soldering	350 °C / 5 sec. max.



ROHS compliant	yes
REACH compliant	yes







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